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Dimensions	
L	5.7mm +/-0.4mm
W	5mm +/-0.4mm
T	5mm +/-0.4mm
B	0.6mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 180mm
Packaging Quantity	300

General Information	
Series	KONNEKT KC-LINK Comm COG
Style	KONNEKT
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	600 mg
Notes	2-Chip Standard Orientation.
Chip Size	2220-2
MSL	1

Specifications	
Capacitance	0.066 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	1000 VDC
Dielectric Withstanding Voltage	1200 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	15.1515 GOhms

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